

ABSTRACT OF THE DISCLOSURE

An integrated circuit package having central leads comprises a substrate has an upper surface, a lower surface, and a long slot penetrating the upper surface to the lower surface. The lower surface is forming with wiring regions arranged at 5 the two sides of the long slot, and the wiring regions are forming with a plurality of connected points. A glue layer is coated on the upper surface of the substrate and is arranged at the periphery of the long slot. The integrated circuit has a first surface forming with a plurality of bonding pads, which is adhered to the glue layer. The wires, each of which is arranged within the long slot of the substrate 10 and is electrically connected the bonding pad of the integrated circuit to the connected point of the substrate ; and The first compound layer is filled within the long slot of the substrate for protecting the each wire.